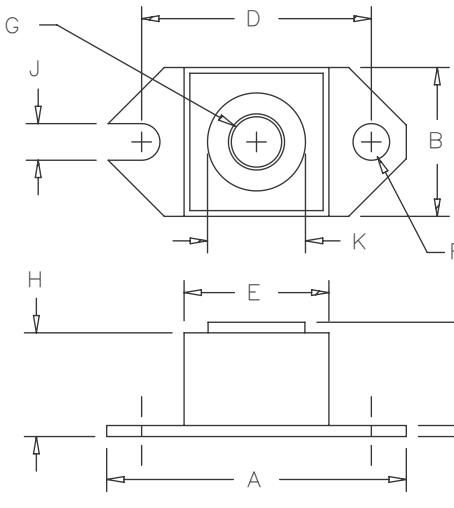
240 Amp Schottky Rectifier

HS246150



Std. Polarity
Base is cathode
Rev. Polarity
Base is anode

Dim.	Inches		Millimeter		
	Minimum	Maximum	Minimum	Maximum	Notes
A	1.52	1.56	38.61	39.62	
B	.725	.775	18.42	19.69	
C	.605	.625	15.37	15.88	
D	1.182	1.192	30.02	30.28	
E	.745	.755	18.92	19.18	Sq.
F	.152	.160	3.86	4.06	Dia.
G		1/4–20	UNC–2B		
H	.525	.580	13.34	14.73	
J	.156	.160	3.96	4.06	
K	.495	.505	12.57	12.83	Dia.
L	.120	.130	3.05	3.30	

Microsemi Catalog Number	Industry Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
HS246150*	249NQ150	150V	150V

*Add Suffix R for Reverse Polarity

- Schottky Barrier Rectifier
- Guard Ring Protection
- 240 Amperes 150 Volts
- 175°C Junction Temperature
- Reverse Energy Tested
- ROHS Compliant

Electrical Characteristics

Average forward current	$I_{F(AV)}$ 240 Amps	T_C = 118°C, Square wave, $R_{\theta JC}$ = .24°C/W
Maximum surge current	I_{FSM} 3300 Amps	8.3ms, half sine, T_J = 175°C
Maximum repetitive reverse current	$I_{R(OV)}$ 2 Amps	f = 1 KHZ, 25°C
Typical peak forward voltage	V_{FM} 0.65 Volts	I_{FM} = 240A: T_J = 175°C*
Max peak forward voltage	V_{FM} 0.86 Volts	I_{FM} = 240A: T_J = 25°C*
Typical peak reverse current	I_{RM} 150mA	V_{RRM}, T_J = 125°C*
Max peak reverse current	I_{RM} 8.0mA	V_{RRM}, T_J = 25°C
Typical junction capacitance	C_J 6000pF	V_R = 5.0V, T_C = 25°C

*Pulse test: Pulse width 300μsec, Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range	T_{STG}	−55°C to 175°C
Operating junction temp range	T_J	−55°C to 175°C
Max thermal resistance	$R_{\theta JC}$	0.21°C/W Junction to case
Typical thermal resistance (greased)	$R_{\theta CS}$	0.12°C/W Case to sink
Terminal Torque		35–40 inch pounds
Mounting Base Torque		20–25 inch pounds
Weight		1.1 ounces (32 grams) typical

HS246150

Figure 1
Typical Forward Characteristics

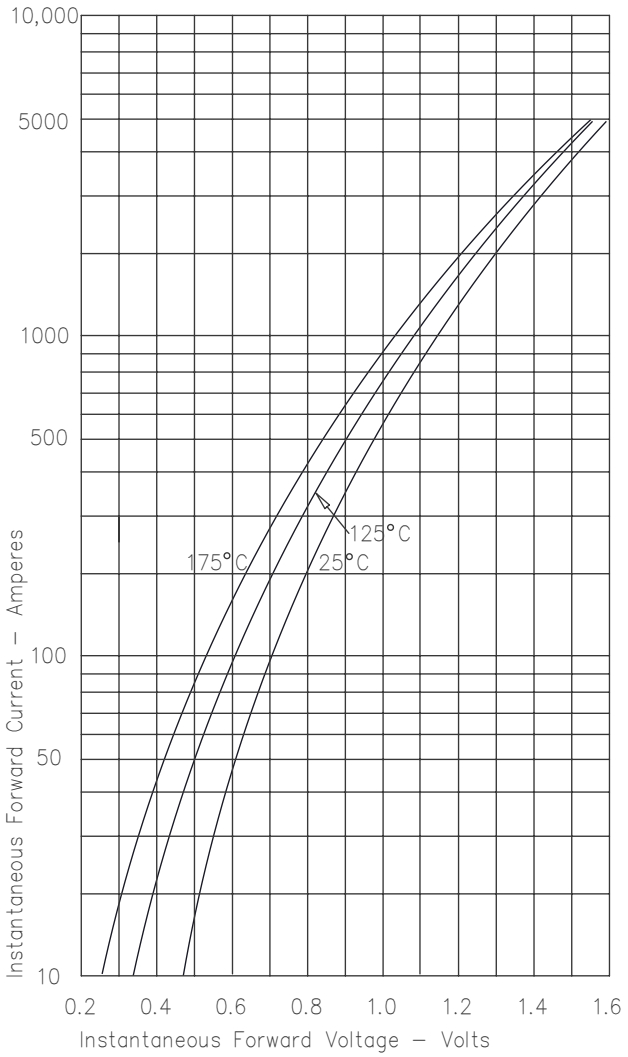


Figure 2
Typical Reverse Characteristics

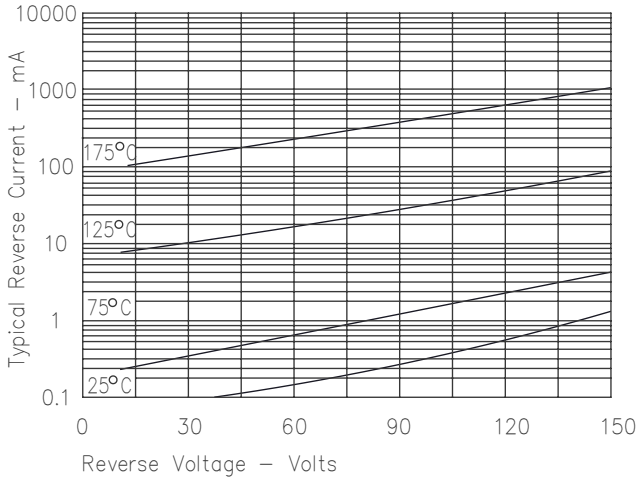


Figure 3
Typical Junction Capacitance

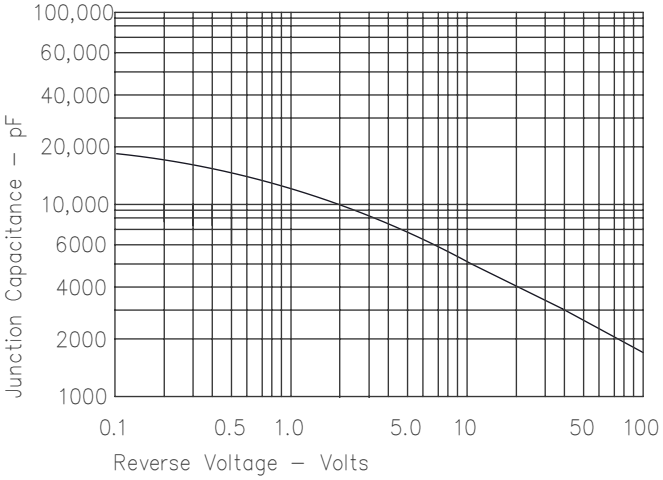


Figure 4
Forward Current Derating

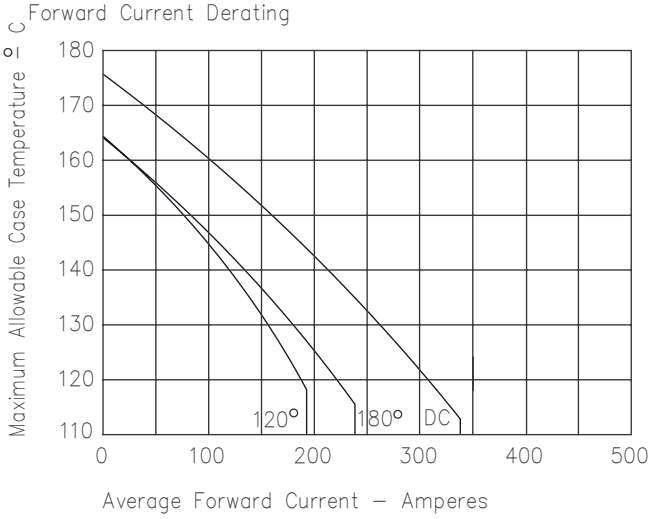
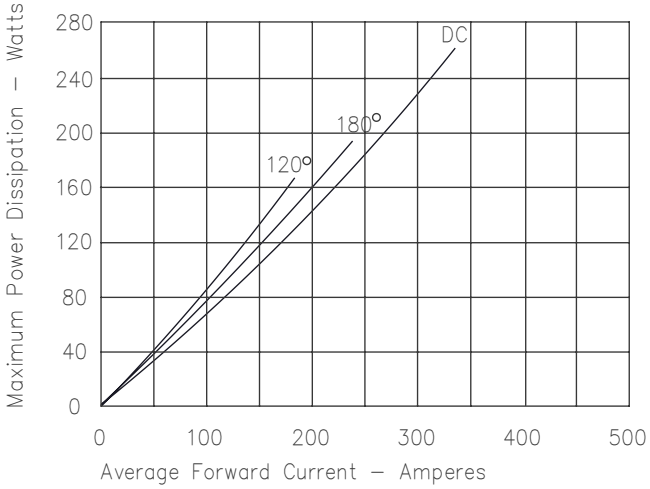


Figure 5
Maximum Forward Power Dissipation



DISCLAIMER

The information contained in the document (unless it is publicly available on the Web without access restrictions) is PROPRIETARY AND CONFIDENTIAL information of Microsemi and cannot be copied, published, uploaded, posted, transmitted, distributed or disclosed or used without the express duly signed written consent of Microsemi. If the recipient of this document has entered into a disclosure agreement with Microsemi, then the terms of such Agreement will also apply. This document and the information contained herein may not be modified, by any person other than authorized personnel of Microsemi. No license under any patent, copyright, trade secret or other intellectual property right is granted to or conferred upon you by disclosure or delivery of the information, either expressly, by implication, inducement, estoppels or otherwise. Any license under such intellectual property rights must be approved by Microsemi in writing signed by an officer of Microsemi.

Microsemi reserves the right to change the configuration, functionality and performance of its products at anytime without any notice. This product has been subject to limited testing and should not be used in conjunction with life-support or other mission-critical equipment or applications. Microsemi assumes no liability whatsoever, and Microsemi disclaims any express or implied warranty, relating to sale and/or use of Microsemi products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Any performance specifications believed to be reliable but are not verified and customer or user must conduct and complete all performance and other testing of this product as well as any user or customers final application. User or customer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the customer's and user's responsibility to independently determine suitability of any Microsemi product and to test and verify the same. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the User. Microsemi specifically disclaims any liability of any kind including for consequential, incidental and punitive damages as well as lost profit. The product is subject to other terms and conditions which can be located on the web at http://www.microsemi.com/legal/tnc.asp

Life Support Application

Seller's Products are not designed, intended, or authorized for use as components in systems intended for space, aviation, surgical implant into the body, in other applications intended to support or sustain life, or for any other application in which the failure of the Seller's Product could create a situation where personal injury, death or property damage or loss may occur (collectively "Life Support Applications").
Buyer agrees not to use Products in any Life Support Applications and to the extent it does it shall conduct extensive testing of the Product in such applications and further agrees to indemnify and hold Seller, and its officers, employees, subsidiaries, affiliates, agents, sales representatives and distributors harmless against all claims, costs, damages and expenses, and attorneys' fees and costs arising, directly or directly, out of any claims of personal injury, death, damage or otherwise associated with the use of the goods in Life Support Applications, even if such claim includes allegations that Seller was negligent regarding the design or manufacture of the goods.

Buyer must notify Seller in writing before using Seller's Products in Life Support Applications. Seller will study with Buyer alternative solutions to meet Buyer application specification based on Sellers sales conditions applicable for the new proposed specific part.